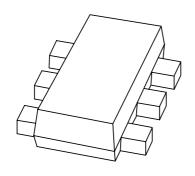
DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS2515VS15 V low V_{CE(sat)} NPN double transistor

Product specification Supersedes data of 2001 Nov 07

2004 Dec 23





15 V low V_{CE(sat)} NPN double transistor

PBSS2515VS

FEATURES

- 300 mW total power dissipation
- Very small 1.6 × 1.2 mm ultra thin package
- · Excellent coplanarity due to straight leads
- · Low collector-emitter saturation voltage
- · High current capability
- Improved thermal behaviour due to flat lead
- Replaces two SC-75/SC-89 packaged low V_{CEsat} transistors on same PCB area
- · Reduces required PCB area
- · Reduced pick and place costs.

APPLICATIONS

- · General purpose switching and muting
- Low frequency driver circuits
- · LCD backlighting
- · Audio frequency general purpose amplifier applications
- Battery driven equipment (mobile phones, video cameras and hand-held devices).

DESCRIPTION

NPN low V_{CEsat} double transistor in a SOT666 plastic package.

PNP complement: PBSS3515VS.

MARKING

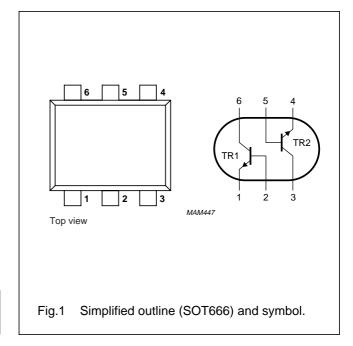
TYPE NUMBER	MARKING CODE
PBSS2515VS	N9

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	15	٧
I _{CM}	peak collector current	1	Α
R _{CEsat}	equivalent on-resistance	<500	mΩ

PINNING

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	



ORDERING INFORMATION

TYPE NUMBER	PACKAGE					
ITTE NOWIDER	NAME	NAME DESCRIPTION VERSION				
PBSS2515VS	_	plastic surface mounted package; 6 leads	SOT666			

15 V low $V_{CE(sat)}$ NPN double transistor

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT		
Per transis	Per transistor unless otherwise specified						
V _{CBO}	collector-base voltage	open emitter	_	15	V		
V _{CEO}	collector-emitter voltage	open base	_	15	V		
V_{EBO}	emitter-base voltage	open collector	_	6	V		
I _C	collector current (DC)		_	500	mA		
I _{CM}	peak collector current		_	1	А		
I _{BM}	peak base current		_	100	mA		
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	200	mW		
T _{stg}	storage temperature		-65	+150	°C		
Tj	junction temperature		_	150	°C		
T _{amb}	operating ambient temperature		-65	+150	°C		
Per device	Per device						
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	300	mW		

Note

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W

Notes

- 1. Transistor mounted on an FR4 printed-circuit board.
- 2. The only recommended soldering method is reflow soldering.

^{1.} Transistor mounted on an FR4 printed-circuit board.

15 V low $V_{\text{CE(sat)}}$ NPN double transistor

PBSS2515VS

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

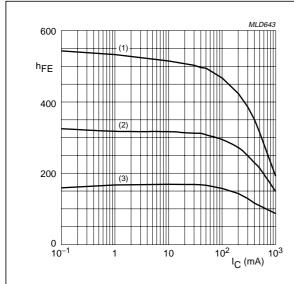
SYMBOL	PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Per transis	Per transistor unless otherwise specified						
I _{CBO}	collector-base cut-off current	V _{CB} = 15 V; I _E = 0 A	_	-	100	nA	
		V _{CB} = 15 V; I _E = 0 A; T _j = 150 °C	_	_	50	μΑ	
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	_	_	100	nA	
h _{FE}	DC current gain	V _{CE} = 2 V; I _C = 10 mA	200	_	_		
		V _{CE} = 2 V; I _C = 100 mA; note 1	150	_	_		
		$V_{CE} = 2 \text{ V}; I_{C} = 500 \text{ mA}; \text{ note 1}$	90	_	_		
V _{CEsat}	collector-emitter saturation	$I_C = 10 \text{ mA}; I_B = 0.5 \text{ mA}$	_	_	25	mV	
	voltage	I _C = 200 mA; I _B = 10 mA	_	_	150	mV	
		$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}; \text{ note 1}$	_	_	250	mV	
R _{CEsat}	equivalent on-resistance	$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}; \text{ note 1}$	_	300	<500	mΩ	
V _{BEsat}	base-emitter saturation voltage	$I_C = 500 \text{ mA}$; $I_B = 50 \text{ mA}$; note 1	_	_	1.1	V	
V _{BE}	base-emitter turn-on voltage	V _{CE} = 2 V; I _C = 100 mA; note 1	_	_	0.9	V	
f _T	transition frequency	I _C = 100 mA; V _{CE} = 5 V; f = 100 MHz	250	420	_	MHz	
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0 \text{ A}; f = 1 \text{ MHz}$	_	4.4	6	pF	

Note

^{1.} Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

15 V low $V_{CE(sat)}$ NPN double transistor

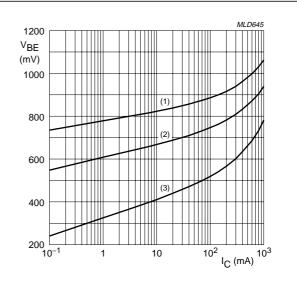
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V_{CE} = 2 V.

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) T_{amb} = 25 °C.
- (3) $T_{amb} = -55$ °C.

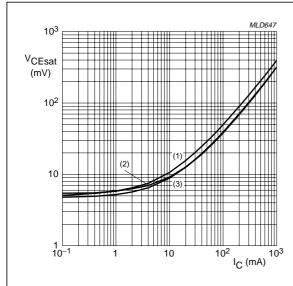
Fig.2 DC current gain as a function of collector current; typical values.



 $V_{CE} = 2 V$.

- (1) $T_{amb} = -55 \, ^{\circ}C$.
- (2) T_{amb} = 25 °C.
- (3) $T_{amb} = 150 \, ^{\circ}C$.

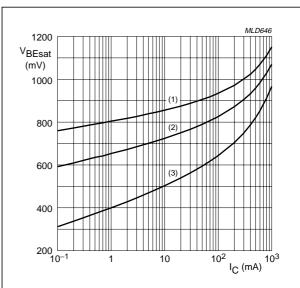
Fig.3 Base-emitter voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.4 Collector-emitter saturation voltage as a function of collector current; typical values.



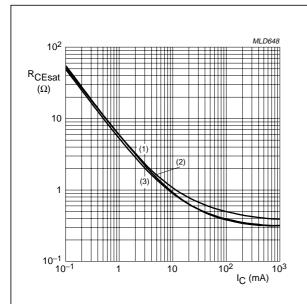
 $I_{\rm C}/I_{\rm B}=20.$

- (1) $T_{amb} = 150 \,^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \,^{\circ}C$.

Fig.5 Base-emitter saturation voltage as a function of collector current; typical values.

15 V low $V_{CE(sat)}$ NPN double transistor

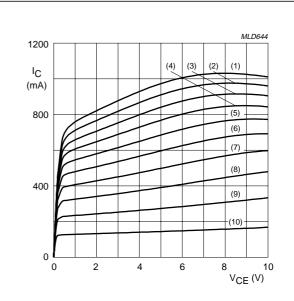
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 $I_{\rm C}/I_{\rm B}=20.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.6 Equivalent on-resistance as a function of collector current; typical values.



 $T_{amb} = 25 \, ^{\circ}C.$

- (1) $I_B = 4.6 \text{ mA}.$
- (6) $I_B = 2.3 \text{ mA}.$
- (2) $I_B = 4.14 \text{ mA}.$
- (7) $I_B = 1.84 \text{ mA}.$
- (3) $I_B = 3.68 \text{ mA}.$
- (8) $I_B = 1.38 \text{ mA}.$
- (4) $I_B = 3.22 \text{ mA}.$
- (9) $I_B = 0.92 \text{ mA}.$
- (5) $I_B = 2.76 \text{ mA}.$
- (10) $I_B = 0.46 \text{ mA}$.

Fig.7 Collector current as a function of collector-emitter voltage; typical values.

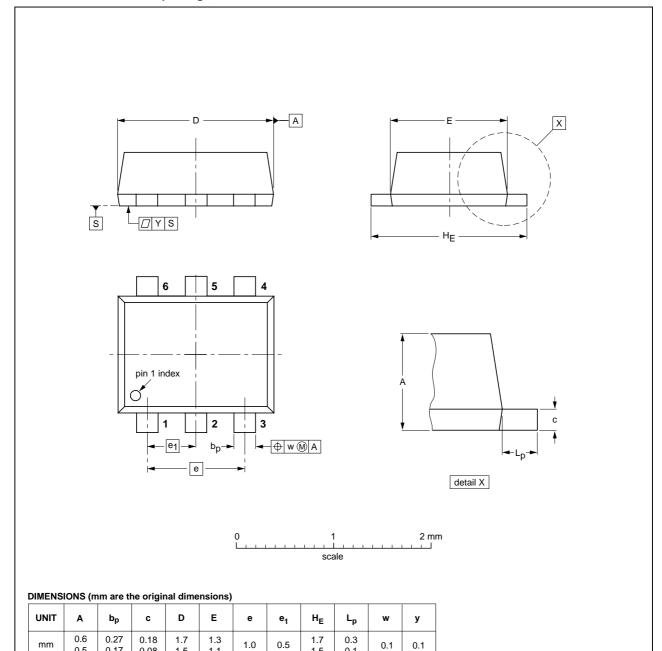
15 V low $V_{CE(sat)}$ NPN double transistor

PBSS2515VS

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT666



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT666						-01-08-27- 04-11-08

15 V low V_{CE(sat)} NPN double transistor

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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